

Title (en)
Semiconductor module.

Title (de)
Halbleitermodul.

Title (fr)
Module semi-conducteur.

Publication
EP 0376365 B1 19950809 (EN)

Application
EP 89203004 A 19891127

Priority
• NL 8802957 A 19881201
• NL 8802958 A 19881201

Abstract (en)
[origin: EP0376365A1] Multichip module with provisions for improved cooling and interconnection so as to allow for maximum chip packaging density. Air cooling is brought about by a zig-zag arrangement of groups (6) of thin wire cooling fins (5) mounted on a heat sink layer (3) also providing the necessary mechanical rigidity of the module. Said interconnection means comprises a layer (22) containing diamond grains (23) having high electrical insulating and high thermal conductive properties.

IPC 1-7
H01L 23/367; **H01L 23/373**

IPC 8 full level
H01L 23/36 (2006.01); **H01L 23/367** (2006.01); **H01L 23/373** (2006.01); **H01L 23/467** (2006.01)

CPC (source: EP)
H01L 23/3677 (2013.01); **H01L 23/3732** (2013.01); **H01L 23/467** (2013.01); **H01L 2924/0002** (2013.01)

Citation (examination)
• EP 0285779 A2 19881012 - IBM [US]
• EP 0269065 A2 19880601 - IBM [US]

Cited by
US5353867A; EP0510734A1; GB2276763B; US5205353A; EP0479205A3; DE4333373A1; DE4333373B4; CN113035805A; DE4445849A1; RU2676391C2; EP3944307A1; US6898082B2; WO2014055323A1; US10393409B2; US10677497B2

Designated contracting state (EPC)
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DOCDB simple family (publication)
EP 0376365 A1 19900704; **EP 0376365 B1 19950809**; DE 68923778 D1 19950914; DE 68923778 T2 19960411; JP H0320069 A 19910129

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